



Product data sheet

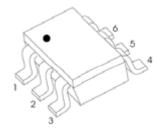
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SOT-363

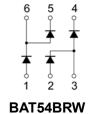


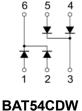
BAT54ADW /BAT54BRW / BAT54CDW /BAT54SDW /BAT54TW BAT54DW/BAT54JW

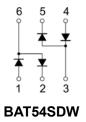
SCHOTTKY BARRIER DIODE ARRAYS FEATURES

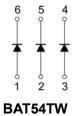
- Low Forward Voltage Drop
- Fast Switching
- Small Surface Mount Package
- PN Junction Guard Ring for Transient and ESD Protection
- Available in Lead Free Version











BAT54ADW

BAT54DW

BAT54JW

MAXIMUM RATINGS (T_a=25℃ unless otherwise noted)

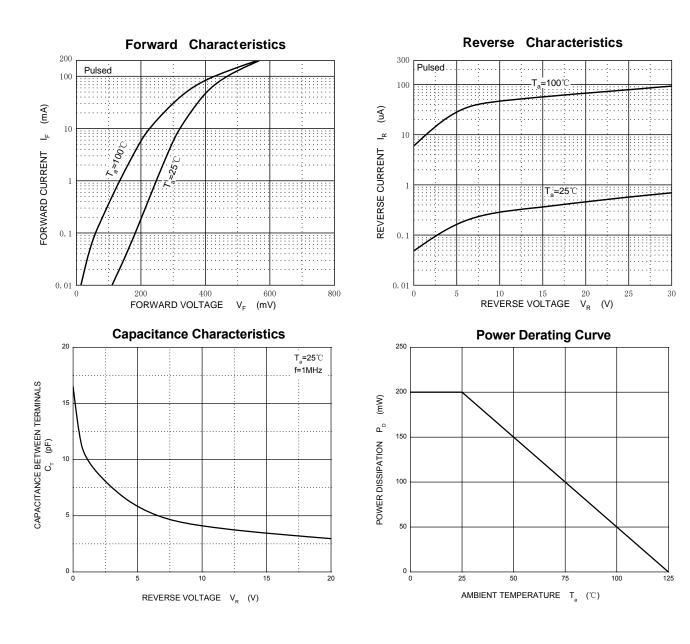
Symbol	Parameter	Value	Unit	
V _{RRM}	Repetitive Peak Reverse Voltage			
V _{RWM}	Peak Working Reverse Voltage	30	V	
VR	DC Blocking Voltage	1		
lo	Forward Continuous Current	200	mA	
I _{FRM}	Repetitive Peak Forward Current	300	mA	
I _{FSM}	Non-repetitive Peak Forward Surge Current @t=8.3ms	600	IIIA	
PD	Power Dissipation	200	mW	
R _{OJA}	Thermal Resistance From Junction To Ambient 500 °C/W		°C/W	
Tj	Operating Junction Temperature Range	-40 ~ +125	°C	
T _{stg}	Storage Temperature Range	-55 ~ +150	°C	



BAT54XXW Semiconductor

ELECTRICAL CHARACTERISTICS (T_a=25 $^{\circ}$ C unless otherwise specified)

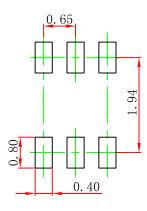
Parameter	Symbol	Test conditions	Min	Тур	Max	Unit
Reverse voltage	V _(BR)	I _R =100μA	30			V
Reverse current	I _R	V _R =25V			2	μA
	VF	I _F =1mA			320	mV
		I _F =10mA			400	
Forward voltage		I _F =30mA			500	
		I _F =100mA			1000	
Total capacitance	C _{tot}	V _R =1V,f=1MHz			10	pF
Reverse recovery time	t _{rr}	I _F = I _R =10mA, I _{rr} =0.1×I _R , R _L =100Ω			5	ns

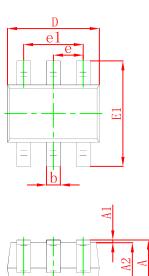






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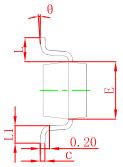




Note:

Controlling dimension:in millimeters.
 General tolerance:± 0.05mm.

3. The pad layout is for reference purposes only.



Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
A	0.900	1.100	0.035	0.043	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.000	0.035	0.039	
b	0.150	0.350	0.006	0.014	
С	0.100	0.150	0.004	0.006	
D	2.000	2.200	0.079	0.087	
E	1.150	1.350	0.045	0.053	
E1	2.150	2.400	0.085	0.094	
е	0.650) TYP	0.020	6 TYP	
e1	1.200	1.400	0.047	0.055	
L	0.525 REF		0.021 REF		
L1	0.260	0.460	0.010	0.018	
θ	0°	8°	0°	8°	

REEL SPECIFICATION

P/N	PKG	QTY
BAT54XXW	SOT-363	3000





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